Contact Name  Title - Contact  Product-Env-Stewards  Authorized Representative*  Product-Env-Stewards  Product Enviro Compliance  Title - Representative  Phone - Contact*  Phone - Contact*  Product-Env-Stewards@onsemi.com  Phone - Representative*  Email - Representative*  Product-Env-Stewards  Product-Env-Stewards@onsemi.com  Requester Item Number  Mfr Item Number  Mfr Item Name  Effective Date  Version  Manufacturing Site  Weight*  UOM  U	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
Company name* Company unique ID  Unique ID Authority  Response Date*  2024-05-09  Contact Name  Title - Contact  Phone - Contact*  Phone - Contact*  Product-Env-Stewards  Product Env-Stewards  Product Env-Stewards  Product Env-Stewards  Product Enviro Compliance  NA  Product Env-Stewards  NA  Product-Env-Stewards  Product-Env-Stewards  Product-Env-Stewards  Product-Env-Stewards  Naunifacturing Site  Weight*  UOM  U  Wanufacturing Proccess Information  Vanufacturing Proccess Information  Peak Process Body Temperature  Max Time at Peak Temperature  Number of Reflow Cycles  Number of Reflow Cycles  Matte Tin (Sn) - annealed  CU Alloy  1 260 C 30 seconds 3	752-21.1											als and Mi	fg Informat	ion	
Insemi	upplier Inform	ation													
Title - Contact Name Product-Env-Stewards Product-E	Company name*				Company unique ID			Unique ID Authority				Response Date*			
Product Env-Stewards	nsemi											2024-05-09			
Authorized Representative*  Product-Env-Stewards  Requester Item Number  Mfr Item Number  Manufacturing Site  Weight*  UOM  U  Manufacturing Proccess Information  Manufacturing Proccess Information  Ferminal Plating / Grid Array Material  Terminal Base Alloy  J-STD-020 MSL Rating  Peak Process Body Temperature  Max Time at Peak Temperature  Number of Reflow Cycles  Matte Tin (Sn) - annealed  CU Alloy  1 260 C 30 seconds 3	ontact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product Envi-Stewards  Requester Item Number  Mfr Item Number  Manufacturing Site  Weight*  UOM  U  Manufacturing Process Information  Manufacturing Site  Weight*  Womper Item  Number of Reflow Cycles  Matte Tin (Sn) - annealed  CU Alloy  1 260 C 30 seconds 3	Product-Env-Stewa	rds		Product Enviro Compliance			]	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	uthorized Represe	ntative*	Title - Representative			I	Phone - Representative*			Email - Representative*					
NSS20201LT1G   20V NPN LOW VCE(SAT) XTR   2024-05-09   CN1   8.13   mg   Ea	Product-Env-Stewa	rds		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles  Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requeste	r Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	N	Anufacturing Site	1	Weight*	UOM	Unit Type
Terminal Plating / Grid Array Material  Terminal Base Alloy  J-STD-020 MSL Rating  Peak Process Body Temperature  Max Time at Peak Temperature  Number of Reflow Cycles  260  C  Somments		NSS20201LT1G 20V NPN LOW VCE(		CE(SAT) XTR		2024-05-09		C	CN1		3.13	mg	Each		
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 comments				arminal Rasa	Alloy	STD 020 MSI	Pating	Dank Proc	eass Rady T	Camparatur	a May Time at Peak	Tamparati	ura Numb	per of Peflow Cyc	dae
omments	5 -			·		31D-020 MSL	. Katilig						bei of Kellow Cyc	les	
	•	i (Sii) - aimealeu		U Alluy	1			200		Ic	30	secon	18 3		
ver 1 - maximum ume at peak temperature during soldering is 10-30 seconds		ima at naak tamparatuus	during cal	doring is 10.3	0 seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	led					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true to the best of its knowledges that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	ceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recruired by the					
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the					

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.16	mg	Supplier	Silicon (Si)	7440-21-3		0.16	mg
Lead Frame	2.92	mg	Supplier	Silver (Ag)	7440-22-4		0.5198	mg
			В	Nickel (Ni)	7440-02-0		0.9023	mg
			Supplier	Iron (Fe)	7439-89-6		1.2468	mg
			Supplier	Copper (Cu)	7440-50-8		0.2511	mg
Mold Compound-Black	4.9	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.49	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0245	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.7105	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		3.185	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.49	mg
Plating	0.14	mg	Supplier	Tin (Sn)	7440-31-5		0.14	mg
Wire Bond - Au	0.01	mg	Supplier	Gold (Au)	7440-57-5		0.01	mg